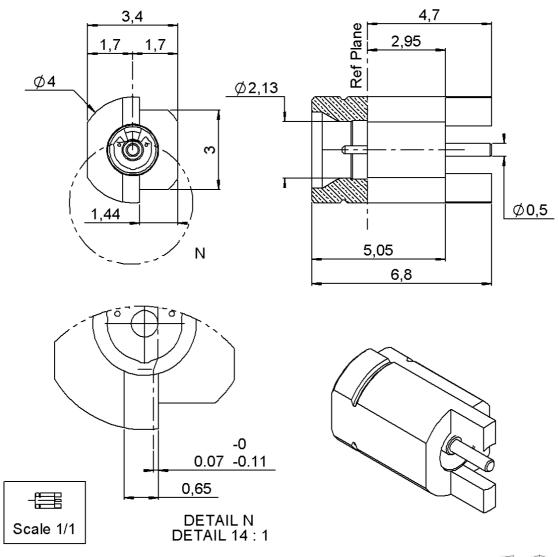
R201.423.110

FULL DETENT-TAPE AND REEL BY 500

Series : **SMPM**



Δ11	dim	ensions	are	in	mm
AII	amı	ensions	are	Ш	иши.

COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BERYLLIUM COPPER BERYLLIUM COPPER PEEK	GOLD 0.5 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2
-	- -	-

Issue: 1349

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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PACKAGING

Standard Unit Other 500 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-40} \;\; \text{GHz} \end{array}$

VSWR 1.3* + 0,0000 x F(GHz) Maxi

Insertion loss Insertion los Insertion lo

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 500 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

*VSWR: 1.10(DC~26.5GHz);1.3(26.5~40GHz)

**Coaxial transmission line only

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.7 N mini
6.7 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3500** g

Issue: 1349 B

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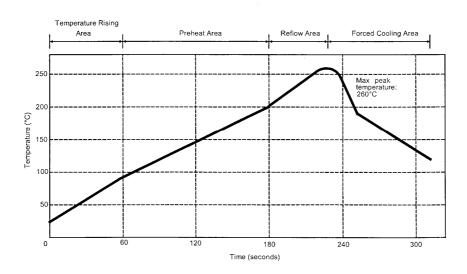
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SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 μ m. Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 1349 B

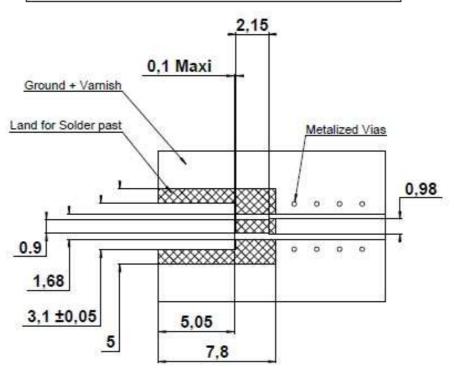
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Recommended PCB Mount



Dimensions applicable for Roger RO4350 PCB material thickness 0.508 mm , with ground layer on bottom . Applicable Frequency - DC to 12Ghz

Issue: 1349 B

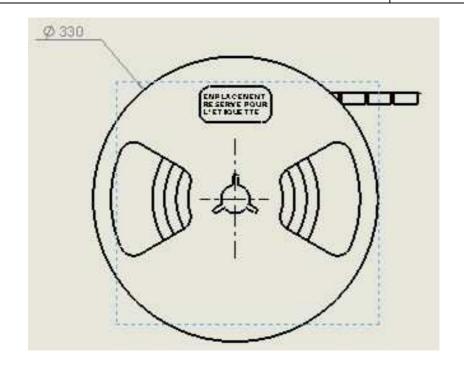
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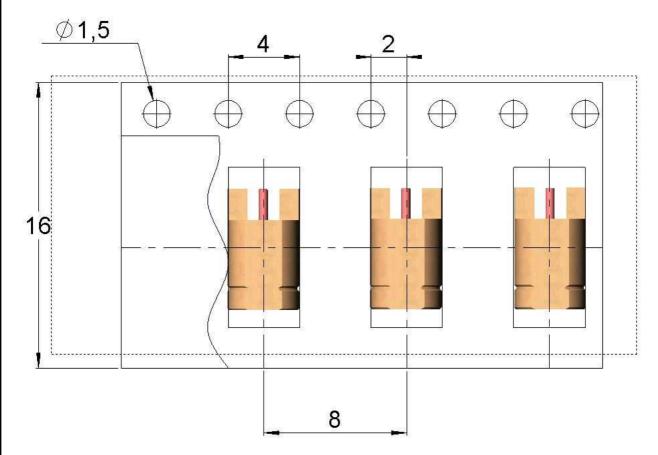


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FULL DETENT-TAPE AND REEL BY 500

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